Special Issue

The Latest Progress in Additive Manufacturing Design, Materials, Processes and Intelligence

Message from the Guest Editors

Additive manufacturing (AM) has achieved notable advancements in both research and industrial sectors, transitioning beyond its initial role in prototyping. Given the rapid expansion of AM technologies, there is a clear need for ongoing updates to the latest scientific developments. This Special Issue invites contributions on recent progress in AM across a range of materials and methodologies with strong translational potential for commercial use, including selective laser sintering, material extrusion, binder jetting, UV curing, hybrid printing methods, and innovative material development to enhance the scope of AM.

Guest Editors

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As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal *Applied Sciences* has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

Editor-in-Chief

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